

Product Change Notification / CENO-190A0R645

Date:

25-Jan-2023

Product Category:

Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6059 Initial Notice: Qualification of EN4900G as a new Bottom Die attach material for selected KSZ8001 and KSZ8721 device families available in 48L TQFP (7x7x1.4mm) package.

Affected CPNs:

CENO-19OAOR645_Affected_CPN_01252023.pdf CENO-19OAOR645_Affected_CPN_01252023.csv

Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of EN4900G as a new Bottom Die attach material for selected KSZ8001 and KSZ8721 device families available in 48L TQFP (7x7x1.4mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Orient	Orient

		Semiconductor Electronics, Ltd (OSE)	Semiconductor Electronics, Ltd (OSE)			
Wire Material		Au	Au			
Die Attack	n Material	8340	EN4900G			
Molding Compound Material		CEL-9200HF	CEL-9200HF			
	Material	C7025	C7025			
Lead-Frame	Paddle Size	160 x160 mils	160 x160 mils			
	See Pre and Post Change Comparison.					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying EN4900G as a new Bottom Die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: May 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2023				>	May 2023					
Workweek	1	2	3	4	5		1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date				х							
Qual Report Availability										х	
Final PCN Issue Date										х	

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 25, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_CENO-19OAOR645_Qual Plan.pdf PCN_CENO-19OAOR645_Pre and Post Change_Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. CENO-19OAOR645 - CCB 6059 Initial Notice: Qualification of EN4900G as a new Bottom Die attach material for selected KSZ8001 and KSZ8721 device families available in 48L TQFP (7x7x1.4mm) package.

Affected Catalog Part Numbers (CPN)

KSZ8001L KSZ8001LJ KSZ8001LJ-TR KSZ8721BL KSZ8721CL KSZ8721BLJ KSZ8721BLJ-TR KSZ8721BLJ-TR